

LIQUID RESIN COMPOSITION FOR SEALING AND ELECTRONIC COMPONENT APPARATUS

ABSTRACT

A liquid resin composition for sealing contains an aliphatic epoxy compound (A), an epoxy compound (B) having an aromatic ring in a molecule, a nitrogen-containing heterocyclic compound (C), and an inorganic filler (D), wherein a percentage content of the inorganic filler (D) is 77% by mass or more with respect to a total mass of the composition.

[No suitable figure]